

# Quad 2-Input NAND Gate

## MM74HC00

### General Description

The MM74HC00 NAND gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs. All devices have high noise immunity and the ability to drive 10 LS-TTL loads. The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

### Features

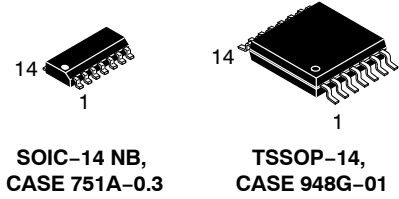
- Typical Propagation Delay: 8 ns
- Wide Power Supply Range: 2 V–6 V
- Low Quiescent Current: 20  $\mu$ A Maximum (74HC Series)
- Low Input Current: 1  $\mu$ A Maximum
- Fanout of 10 LS-TTL Loads
- This Device is Pb-Free and Halide Free

### ABSOLUTE MAXIMUM RATINGS (Note 1)

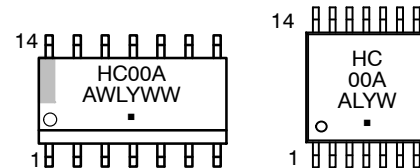
Symbol	Parameter	Rating	Unit
$V_{CC}$	Supply Voltage	-0.5 to +7.0	V
$V_{IN}$	DC Input Voltage	-0.5 to $V_{CC} + 0.5$	V
$V_{OUT}$	DC Output Voltage	-0.5 to $V_{CC} + 0.5$	V
$I_{IK}, I_{OK}$	Clamp Diode Current	$\pm 20$	mA
$I_{OUT}$	DC Output Current, per pin	$\pm 25$	mA
$I_{CC}$	DC $V_{CC}$ or GND Current, per pin	$\pm 50$	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	$^{\circ}$ C
$P_D$	Power Dissipation (Note 2)	600	mW
	S.O. Package only	500	
$T_L$	Lead Temperature (Soldering 10 seconds)	260	$^{\circ}$ C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Unless otherwise specified all voltages are referenced to ground.
2. Power Dissipation temperature derating – plastic “N” package: -12 mW/ $^{\circ}$ C from 65 $^{\circ}$ C to 85 $^{\circ}$ C.



### MARKING DIAGRAM

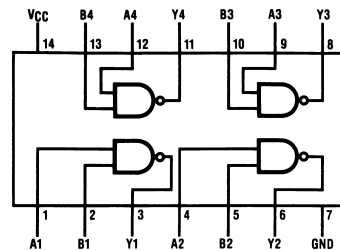


- HC00A = Specific Device Code
- A = Assembly Location
- WL, L = Wafer Lot Number
- Y = Year
- WW, YW = Work Week
- = Pb-Free Package

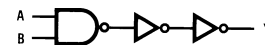
(Note: Microdot may be in either location)

### CONNECTION DIAGRAM

Pin Assignment for SOIC and TSSOP



### LOGIC DIAGRAM



### ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

# MM74HC00

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
$V_{CC}$	Supply Voltage	2	6	V	
$V_{IN}, V_{OUT}$	DC Input or Output Voltage	0	$V_{CC}$	V	
$T_A$	Operating Temperature Range	-40	+85	°C	
$t_r, t_f$	Input Rise or Fall Times	$V_{CC} = 2.0\text{ V}$	-	1000	ns
		$V_{CC} = 4.5\text{ V}$	-	500	
		$V_{CC} = 6.0\text{ V}$	-	400	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS (Note 3)

Symbol	Parameter	$V_{CC}$ (V)	Conditions	$T_A = 25^\circ\text{C}$		$T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$	$T_A = -55^\circ\text{C}$ to $125^\circ\text{C}$	Unit
				Typ.	Guaranteed Limits			
$V_{IH}$	Minimum HIGH Level Input Voltage	2.0		-	1.5	1.5	1.5	V
		4.5		-	3.15	3.15	3.15	
		6.0		-	4.2	4.2	4.2	
$V_{IL}$	Maximum LOW Level Input Voltage	2.0		-	0.5	0.5	0.5	V
		4.5		-	1.35	1.35	1.35	
		6.0		-	1.8	1.8	1.8	
$V_{OH}$	Minimum HIGH Level Output Voltage	2.0	$V_{IN} = V_{IH}$ or $V_{IL}$ , $ I_{OUT}  \leq 20\ \mu\text{A}$	2.0	1.9	1.9	1.9	V
		4.5		4.5	4.4	4.4	4.4	
		6.0		6.0	5.9	5.9	5.9	
		4.5	$V_{IN} = V_{IH}$ or $V_{IL}$ , $ I_{OUT}  \leq 4.0\ \text{mA}$	4.2	3.98	3.84	3.7	
		6.0		$V_{IN} = V_{IH}$ or $V_{IL}$ , $ I_{OUT}  \leq 5.2\ \text{mA}$	5.7	5.48	5.34	
$V_{OL}$	Maximum LOW Level Output Voltage	2.0	$V_{IN} = V_{IH}$ or $V_{IL}$ , $ I_{OUT}  \leq 20\ \mu\text{A}$	0	0.1	0.1	0.1	V
		4.5		0	0.1	0.1	0.1	
		6.0		0	0.1	0.1	0.1	
		4.5	$V_{IN} = V_{IH}$ or $V_{IL}$ , $ I_{OUT}  \leq 4.0\ \text{mA}$	0.2	0.26	0.33	0.4	
		6.0		$V_{IN} = V_{IH}$ or $V_{IL}$ , $ I_{OUT}  \leq 5.2\ \text{mA}$	0.2	0.26	0.33	
$I_{IN}$	Maximum Input Current	6.0	$V_{IN} = V_{CC}$ or GND	-	$\pm 0.1$	$\pm 1.0$	$\pm 1.0$	$\mu\text{A}$
$I_{CC}$	Maximum Quiescent Supply Current	6.0	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0\ \mu\text{A}$	-	2.0	20	40	$\mu\text{A}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. For a power supply of  $5\text{ V} \pm 10\%$  the worst case output voltages ( $V_{OH}$ , and  $V_{OL}$ ) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC} = 5.5\text{ V}$  and 4.5 V respectively. (The  $V_{IH}$  value at 5.5 V is 3.85 V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0 V values should be used.

## AC ELECTRICAL CHARACTERISTICS

( $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ ,  $C_L = 15\text{ pF}$ ,  $t_r = t_f = 6\text{ ns}$ )

Symbol	Parameter	Conditions	Typ.	Guaranteed Limit	Unit
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay		8	15	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# MM74HC00

## AC ELECTRICAL CHARACTERISTICS

( $V_{CC} = 2.0\text{ V to }6.0\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $t_r = t_f = 6\text{ ns}$ , unless otherwise specified)

Symbol	Parameter	$V_{CC}$ (V)	Conditions	$T_A = 25^\circ\text{C}$		$T_A = -40^\circ\text{C}$ to $85^\circ\text{C}$	$T_A = -55^\circ\text{C}$ to $125^\circ\text{C}$	Unit
				Typ.	Guaranteed Limits			
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay	2.0		45	90	113	134	ns
		4.5		9	18	23	27	
		6.0		8	15	19	23	
$t_{TLH}$ , $t_{THL}$	Maximum Output Rise and Fall Time	2.0		30	75	95	110	ns
		4.5		8	15	19	22	
		6.0		7	13	16	19	
$C_{PD}$	Power Dissipation Capacitance (Note 4)		(per gate)	20	-	-	-	pF
$C_{IN}$	Maximum Input Capacitance			5	10	10	10	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4.  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} V_{CC} f + I_{CC}$ .

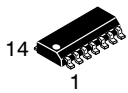
## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MM74HC00M	SOIC-14 NB (Pb-Free and Halide Free)	55 Units / Tube
MM74HC00MX		2500 / Tape & Reel
MM74HC00MTCX	TSSOP-14 (Pb-Free and Halide Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

NOTE: All packages are lead free per JEDEC: J-STD-020B standard.

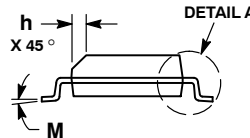
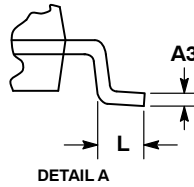
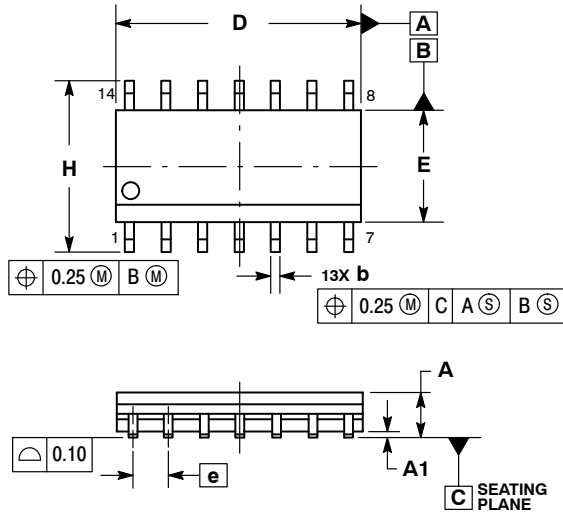
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

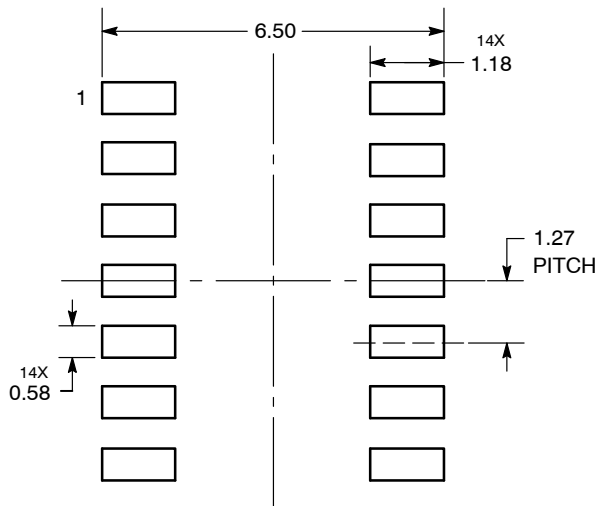


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

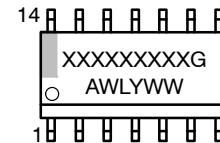
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

DATE 03 FEB 2016

STYLE 1:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. NO CONNECTION  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 2:  
 CANCELLED

STYLE 3:  
 PIN 1. NO CONNECTION  
 2. ANODE  
 3. ANODE  
 4. NO CONNECTION  
 5. ANODE  
 6. NO CONNECTION  
 7. ANODE  
 8. ANODE  
 9. ANODE  
 10. NO CONNECTION  
 11. ANODE  
 12. ANODE  
 13. NO CONNECTION  
 14. COMMON CATHODE

STYLE 4:  
 PIN 1. NO CONNECTION  
 2. CATHODE  
 3. CATHODE  
 4. NO CONNECTION  
 5. CATHODE  
 6. NO CONNECTION  
 7. CATHODE  
 8. CATHODE  
 9. CATHODE  
 10. NO CONNECTION  
 11. CATHODE  
 12. CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 5:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. COMMON ANODE  
 8. COMMON CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 6:  
 PIN 1. CATHODE  
 2. CATHODE  
 3. CATHODE  
 4. CATHODE  
 5. CATHODE  
 6. CATHODE  
 7. CATHODE  
 8. ANODE  
 9. ANODE  
 10. ANODE  
 11. ANODE  
 12. ANODE  
 13. ANODE  
 14. ANODE

STYLE 7:  
 PIN 1. ANODE/CATHODE  
 2. COMMON ANODE  
 3. COMMON CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
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 8. ANODE/CATHODE  
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 13. ANODE/CATHODE  
 14. ANODE/CATHODE

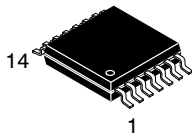
STYLE 8:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. COMMON ANODE  
 8. COMMON ANODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. NO CONNECTION  
 12. ANODE/CATHODE  
 13. ANODE/CATHODE  
 14. COMMON CATHODE

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# MECHANICAL CASE OUTLINE

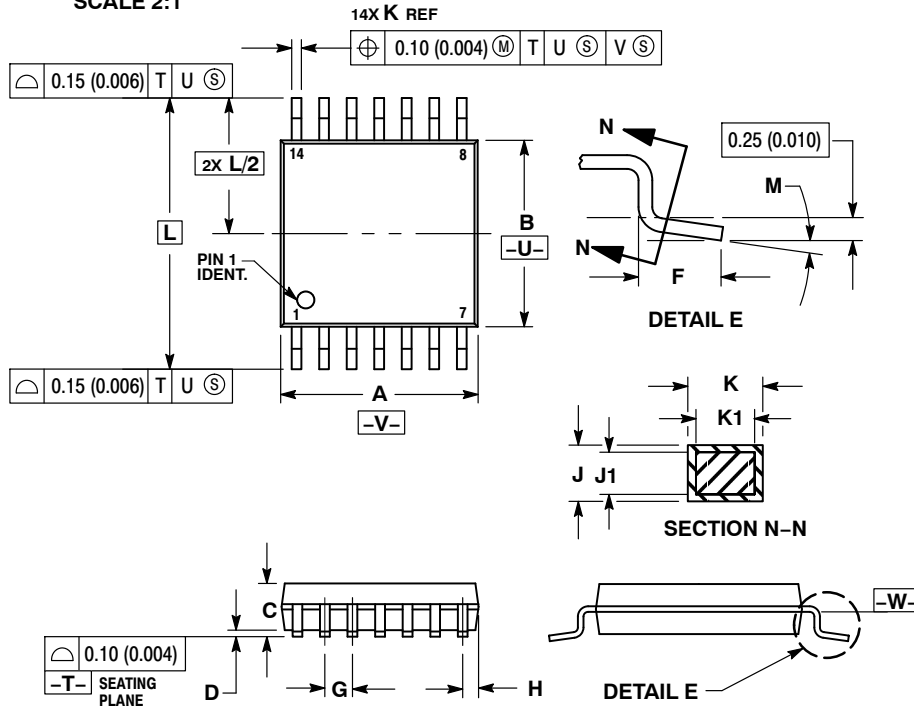
## PACKAGE DIMENSIONS



**TSSOP-14 WB**  
CASE 948G  
ISSUE C

DATE 17 FEB 2016

SCALE 2:1

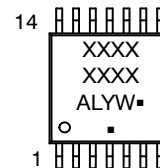


**NOTES:**

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**GENERIC MARKING DIAGRAM\***

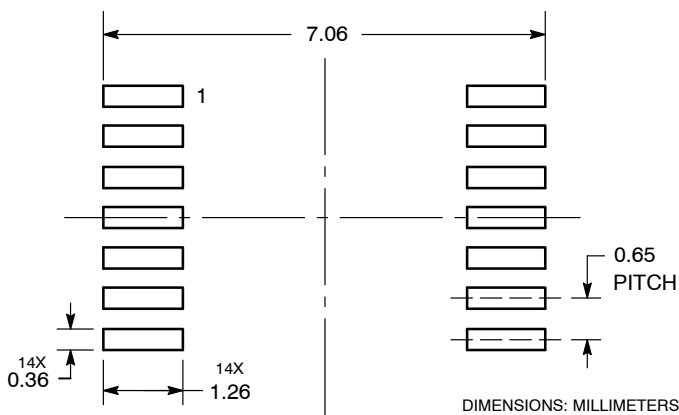


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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